

2827

MEG01-004

Serial number 09/837,007

TO: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

From : George O. Saile (Reg. No. 19,572)
28 Davis Avenue
Poughkeepsie, NY 12603

Date: February 15, 2003

REF: APPLICANT : Mou-Shiung Lin
SERIAL NO. : 09/837,007
ART UNIT : 2827
FILING DATE : 04/18/01
ATT'Y NO. : MEG01-004
EXAMINER : Mitchell, James M.
TITLE : A STRUCTURE AND MANUFACTURING
METHOD OF A CHIP SCALE PACKAGE

AMENDMENT AND RESPONSE TO OFFICE ACTION

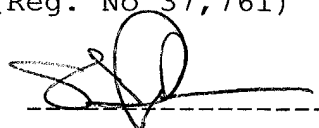
Sir:

In response to an office action mailed on 11/19/02
please consider the following amendments and remarks with
respect to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal service as First
Class mail in an envelop addressed to the Commissioner of
Patents and Trademarks, Washington, D.C. 20231, on
February 19, 2003.

Stephen B. Ackerman (Reg. No 37,761)


Signature

2/19/03
Date

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